



SOT2018-1

HLLGA31R, thermal enhanced low profile land grid array package, 31 terminals, 1 mm pitch, 10 mm x 8 mm x 1.365 mm body

12 April 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HLLGA31R
Package style descriptive code	HLLGA (thermal enhanced low profile land grid array)
Mounting method type	S (surface mount)
Issue date	26-03-2019
Manufacturer package code	98ASA01379D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	10	-	mm
package width	-	8	-	mm
package height	-	1.365	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	31	-	



2 Package outline

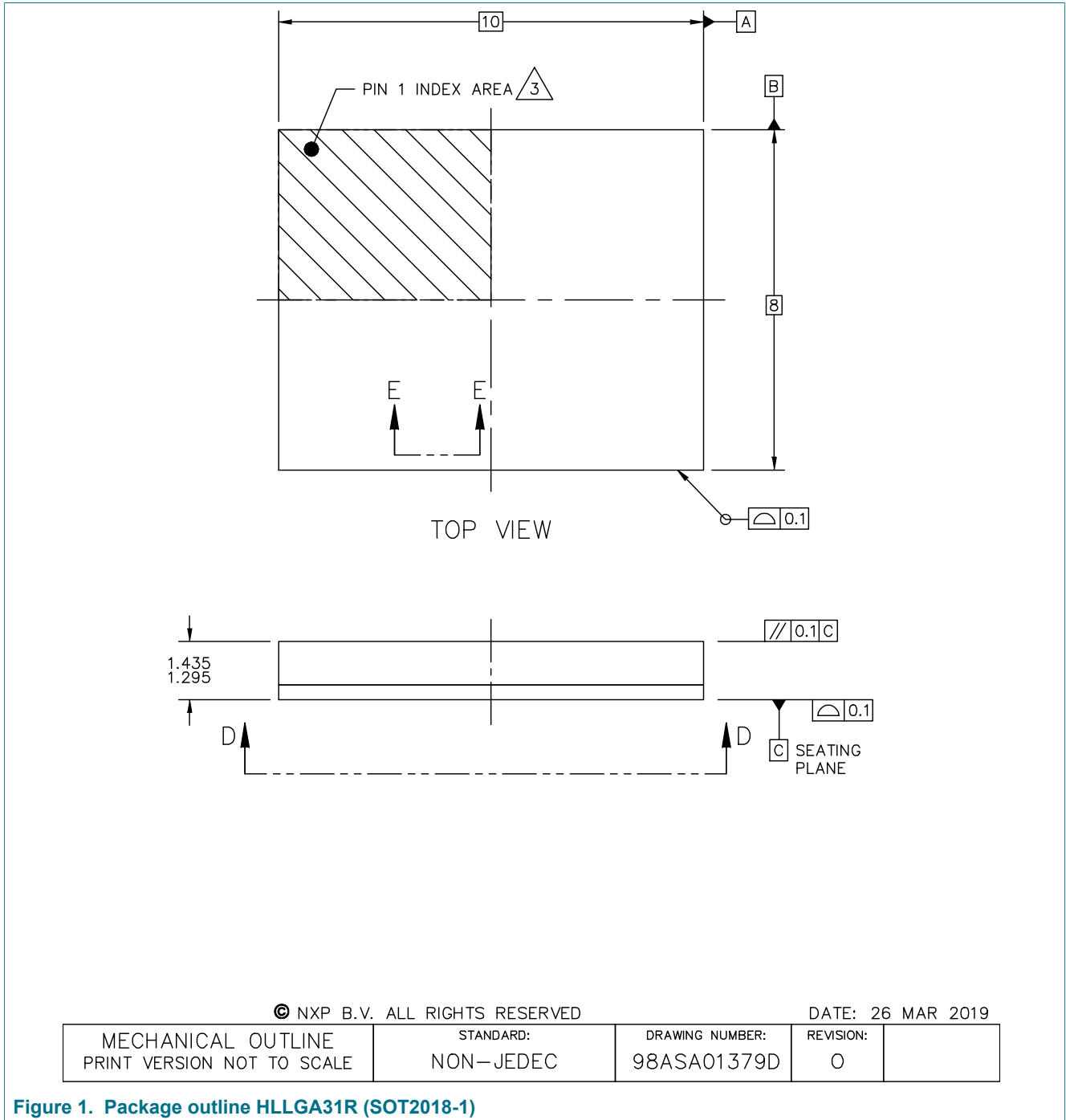


Figure 1. Package outline HLLGA31R (SOT2018-1)

HLLGA31R, thermal enhanced low profile land grid array package, 31 terminals, 1 mm pitch, 10 mm x 8 mm x 1.365 mm body

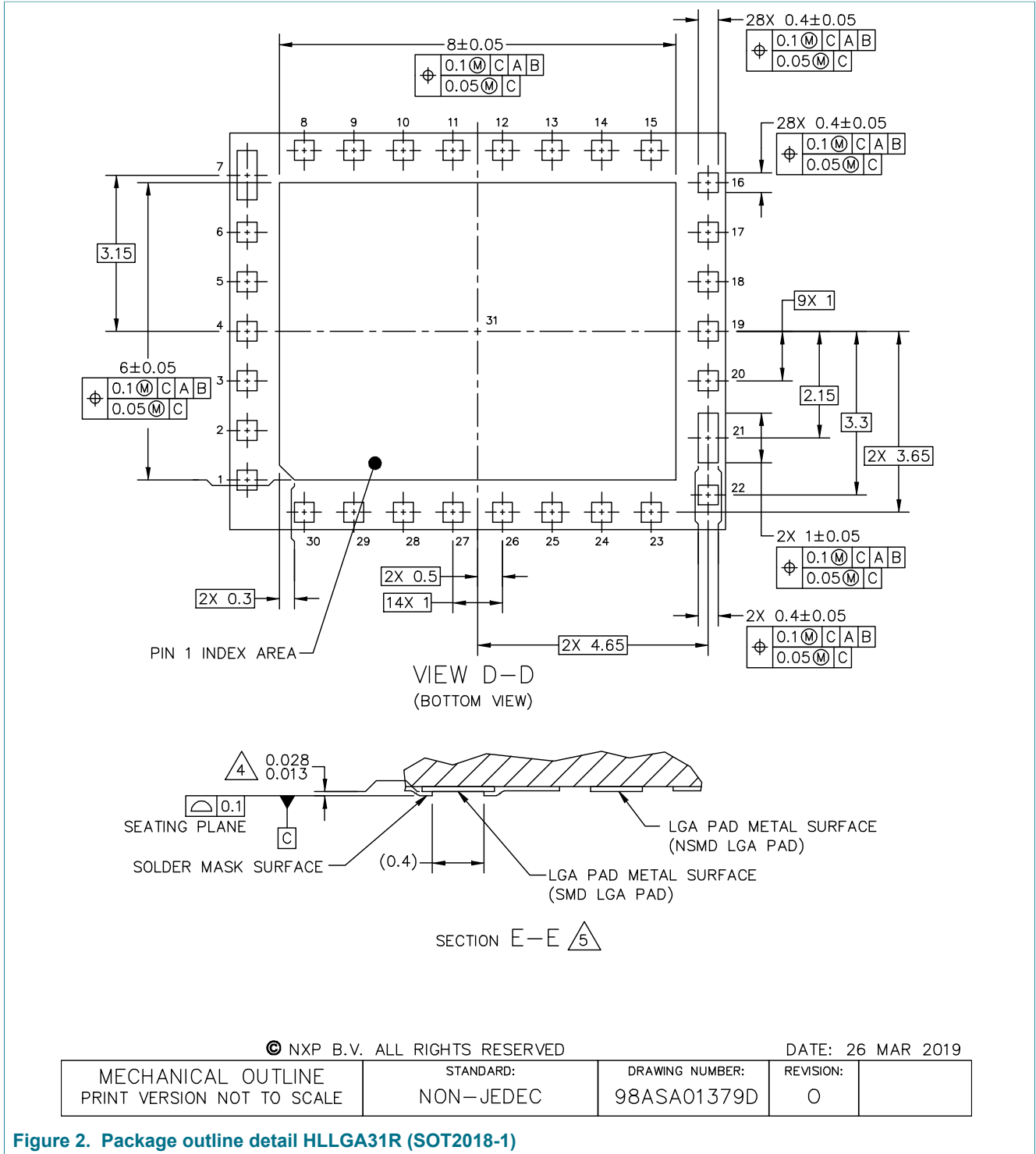


Figure 2. Package outline detail HLLGA31R (SOT2018-1)

3 Soldering

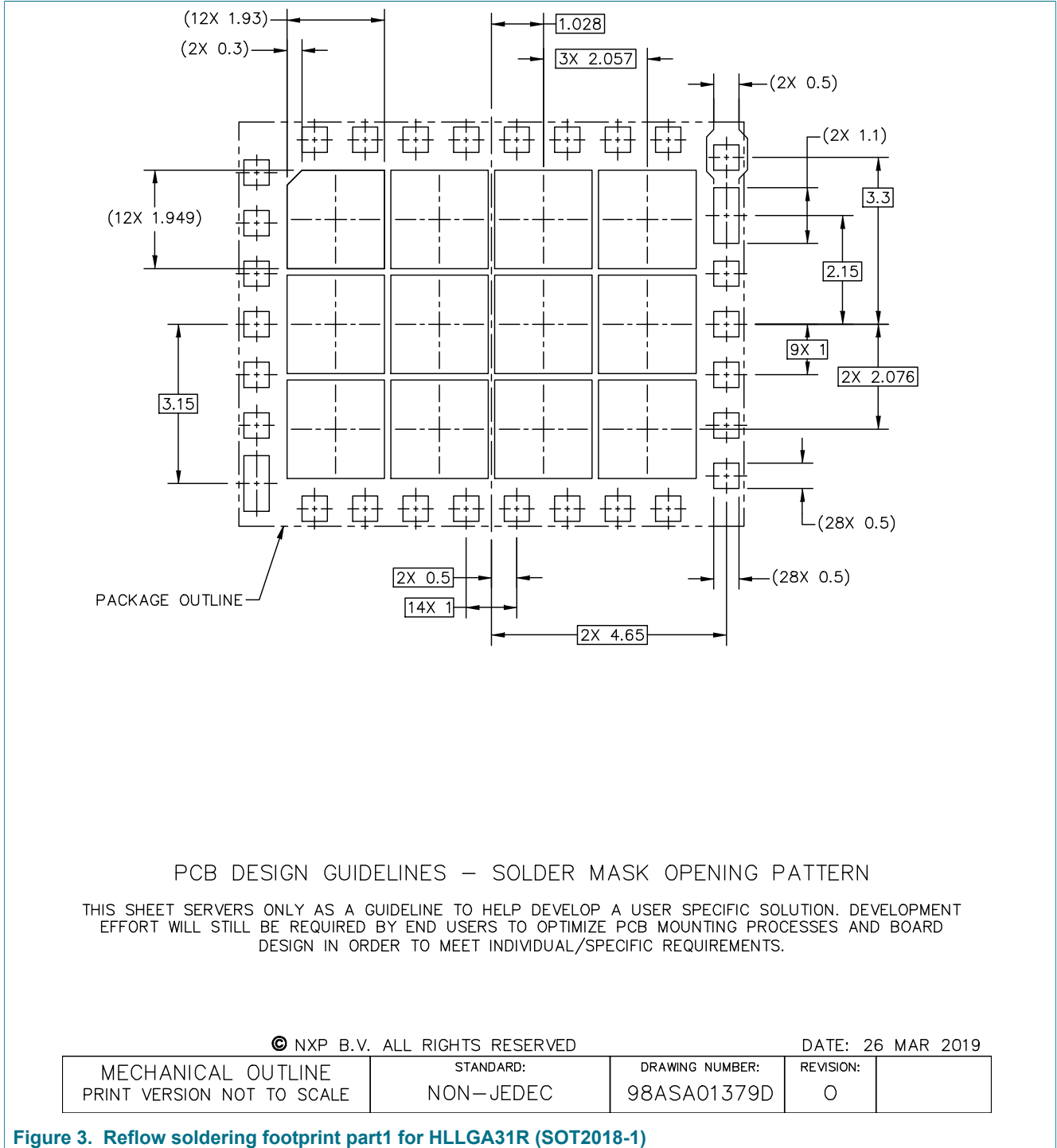
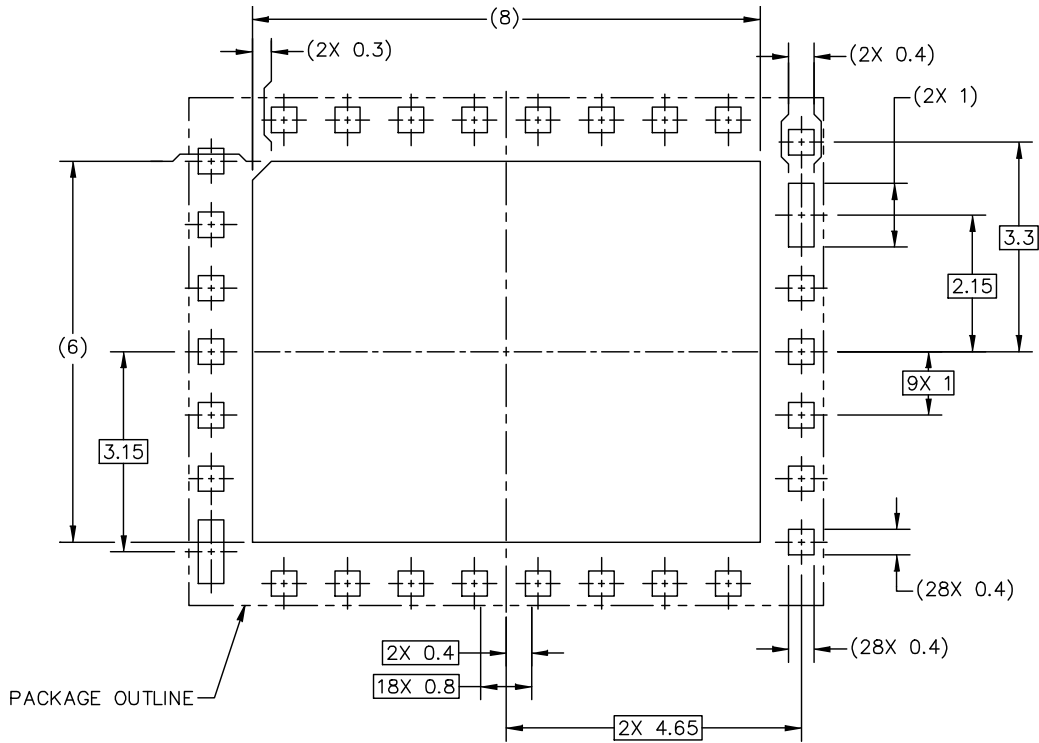


Figure 3. Reflow soldering footprint part1 for HLLGA31R (SOT2018-1)

HLLGA31R, thermal enhanced low profile land grid array package, 31 terminals, 1 mm pitch, 10 mm x 8 mm x 1.365 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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Figure 4. Reflow soldering footprint part2 for HLLGA31R (SOT2018-1)

HLLGA31R, thermal enhanced low profile land grid array package, 31 terminals, 1 mm pitch, 10 mm x 8 mm x 1.365 mm body

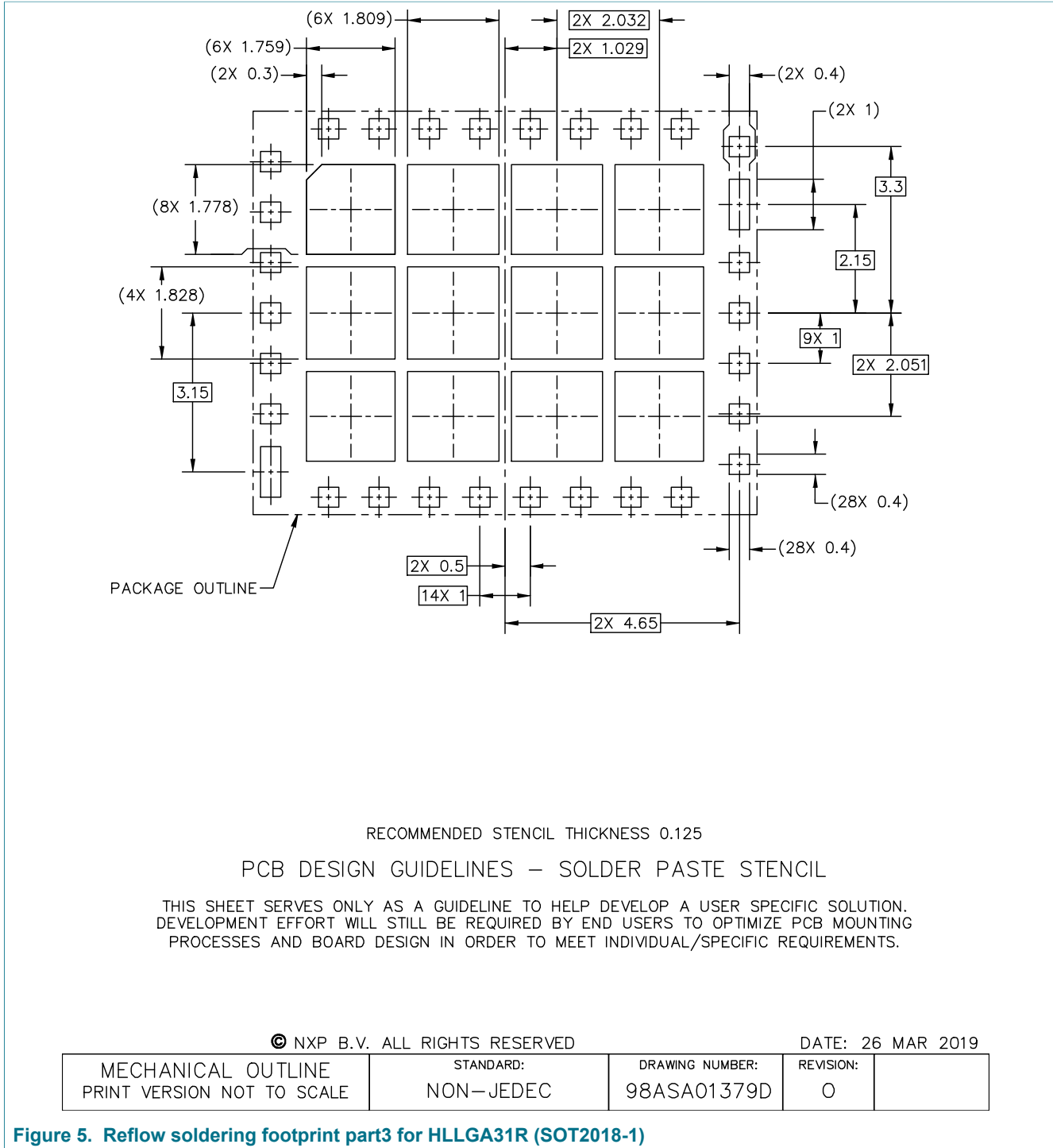


Figure 5. Reflow soldering footprint part3 for HLLGA31R (SOT2018-1)

HLLGA31R, thermal enhanced low profile land grid array package, 31 terminals, 1 mm pitch, 10 mm x 8 mm x 1.365 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS AND FLAG.
5. THE BOTTOM VIEW SHOWS THE SOLDERABLE AREA OF THE PADS. THE CENTER PAD (PIN 31) IS SOLDER MASK DEFINED. SOME PERIPHERAL PADS ARE SOLDER MASK DEFINED (SMD) AND OTHERS ARE NON-SOLDERMASK DEFINED (NSMD).

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Figure 6. Package outline note HLLGA31R (SOT2018-1)

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